

IN THE SPECIFICATION:

note

Please replace paragraph [0025] on page ~~10~~¹¹ of the specification with the following:

E1

[0025] FIGS. 15-17 are cross-sectional views of an adhesive coated lead finger of a LOC semiconductor assembly formed by the inversion method of the present invention;

IN THE CLAIMS:

Claims 26 through 28, 38 through 40, 46, 48 through 50 and 59 through 61 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity. Please enter these claims as amended. Also attached is a version with markings to show changes made to the claims.

Please cancel claims ~~29~~ and ~~51~~ without prejudice or disclaimer.

E2

7. (Previously amended twice) A semiconductor substrate including at least one laterally unconstrained adhesive patch comprised of a viscous adhesive material, the at least one adhesive patch including a first surface adjacent and supported from beneath by said semiconductor substrate and a second, smaller exposed surface opposite said first surface exhibiting a generally planar portion over a substantial portion thereof, said semiconductor substrate including said at least one adhesive patch formed by:
providing a semiconductor substrate;
dispensing a viscous adhesive material on said semiconductor substrate; and
inverting said semiconductor substrate without effecting substantial lateral confinement of said adhesive material and maintaining said semiconductor substrate in an inverted position at least until said viscous adhesive material sufficiently stabilizes so as to exhibit a desired stable shape and a lateral boundary defining sizes of said first and second surfaces of said